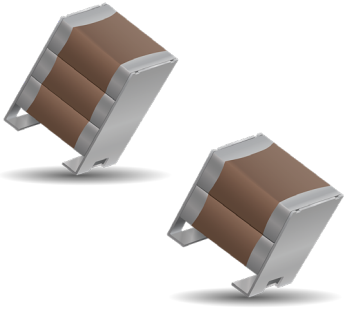


DSCC 25007, Mini BME Stacked Ceramic Capacitors

Defense Logistics Agency Approved



The MB Stack (MBS) range uses KYOCERA AVX's high volumetric efficient and ultra reliable BME X7R 2220 capacitors that can be finished in either a J, L or Paddle (single foot) type lead frame from its Mil Prf 32535 qualified production plant. The MBS range approved under the DSCC 25007 drawing covers the 2-chip horizontal placed capacitors. The range will be expanding once approved to include a 3-chip horizontal and a 3 to 10 chip vertical 1 placed case sized capacitors and are suitable for input or output filtering in Mil/Space based applications and are finished with 100% Group A voltage conditioning as standard. Making these the designers' first choice for high CV capacitors with an ultra-reliable performance as standard for the most demanding applications with Sn/Pb finished lead frames.

FEATURES

- Low ESR/ESL Capability
- Lead frames providing Enhanced Thermo-Mechanical Stress Resistance
- Ability to downsize from traditional large stacked ceramic capacitors
- PCB Space Saving Using Stacked MLCCs, initial range 100 v 10 uF to 25 v 47 uF
- 100 % Voltage condition according to Mil Prf 32535 Group A type as standard, addition Group B can be ordered
- Lead frames, J (J lead 2 feet), L (Lead 2 feet), Paddle single foot G (formed inward) - H (formed outward)

HOW TO ORDER

<u>25007</u>	<u>B</u>	<u>106</u>	<u>M</u>	<u>G</u>	<u>-</u>	<u>\1</u>
Specification Code 25007 = DSCC Spec	Voltage Code Z = 25V A = 50V B = 100V	Capacitance Code 106 = 10uF 226 = 22uF 227 = 220uF	Tolerance M = ±20%	Leads J = Forward inward 2 Feet L = Forward outward 2 Feet G = Paddle inward H = Paddle outward	Group Test Blank = 100% Group A only B = 100% Group A and B	Packaging Blank = Waffle pack \1 = Tape and Reel (A) A = 2 Chip Horizontal Only

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
MINI BME STACKED RANGE (MBS)

Cap u F M Tol	Mini BME Stack Series		
	10/16/25	50	100
8.2			X2 (H only) J, L, G, H
10			X2 (H only) J, L, G, H
12			X3 ² (H, V)
15			X3 ² (H, V)
18		X2 (H only) J, L, G, H	
20		X2 (H only) J, L, G, H	
22		X2 (H, V) J, L, G, H	X5 (V)
27	X2 (H only) J, L, G, H	X3 ² (H, V)	
33	X2 (H only) J, L, G, H	X3 ² (H, V)	
44	X2 (H only) J, L, G, H		
47	X2 (H only) J, L, G, H	X5 (V)	X10 (V)
54	X3 ² (H, V)		
66	X3 ² (H, V)		
82		X10 (V)	
100			
120	X5 (V)		
150			
180			
220	X10 (V)		

Note 1: H = Horizontal, V = Vertical, Tape and Reel 2 Chip stack only

Note 2: X3 Horizontal with J, L, G, H lead frame. X3/5/10 Vertical with J, L only
Preferred solder method, Reflow soldering

 Qualified to DSCC 25007. X2 = 2 X 2220 Stack

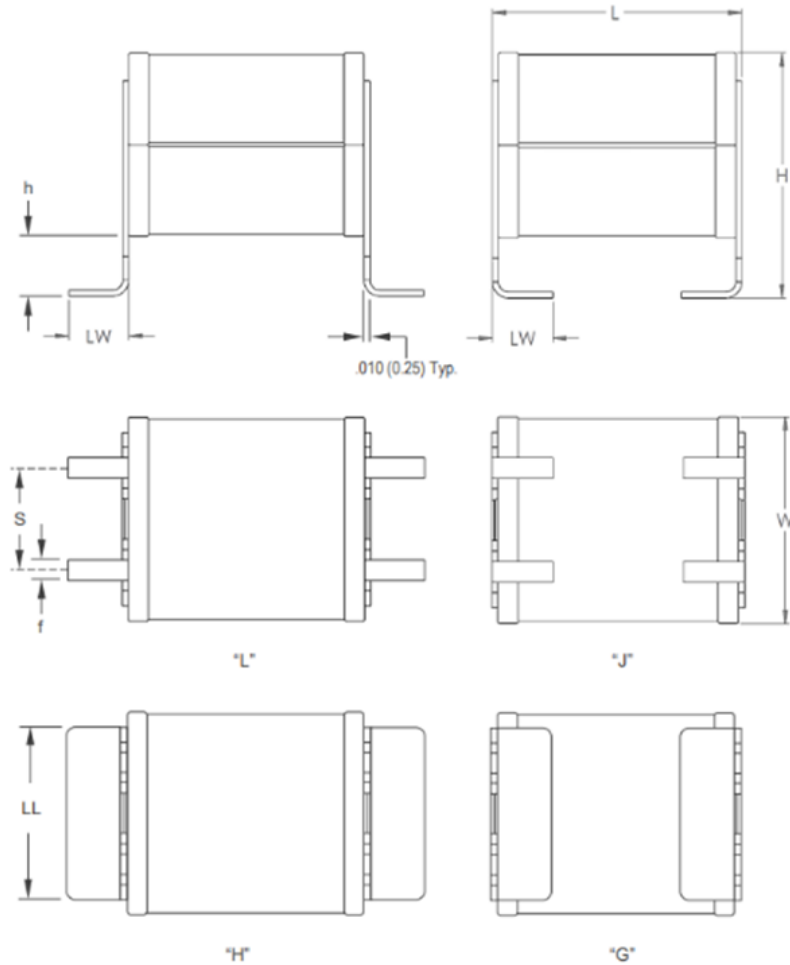
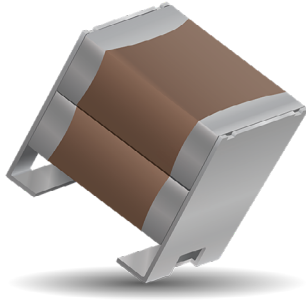
 In qualification to DSCC 25007

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X2, 2 CHIP (2220) HORIZONTAL STACK DIMENSIONS, MM (INCH)



Max Stack Length, L	Max Stack Width, W	Profile Height, h	Lead frame feet distance, S	Lead frame feet, LW	Lead frame feet width, f	Paddle frame feet, LL	Paddle frame feet, LT	Max Stack Height x 2 Chip Stack, H
7.2 (0.283)	5.4 (0.213)	1.50 ± 0.30 (0.059 ± 0.012)	2.54 ± 0.10 (0.100 ± 0.004)	1.50 ± 0.15 (0.059 ± 0.006)	0.51 ± 0.03 (0.02 ± 0.001)	4.1 ± 0.3 (0.161 ± 0.012)	1.50 ± 0.15 (0.059 ± 0.006)	7.5 (0.296)